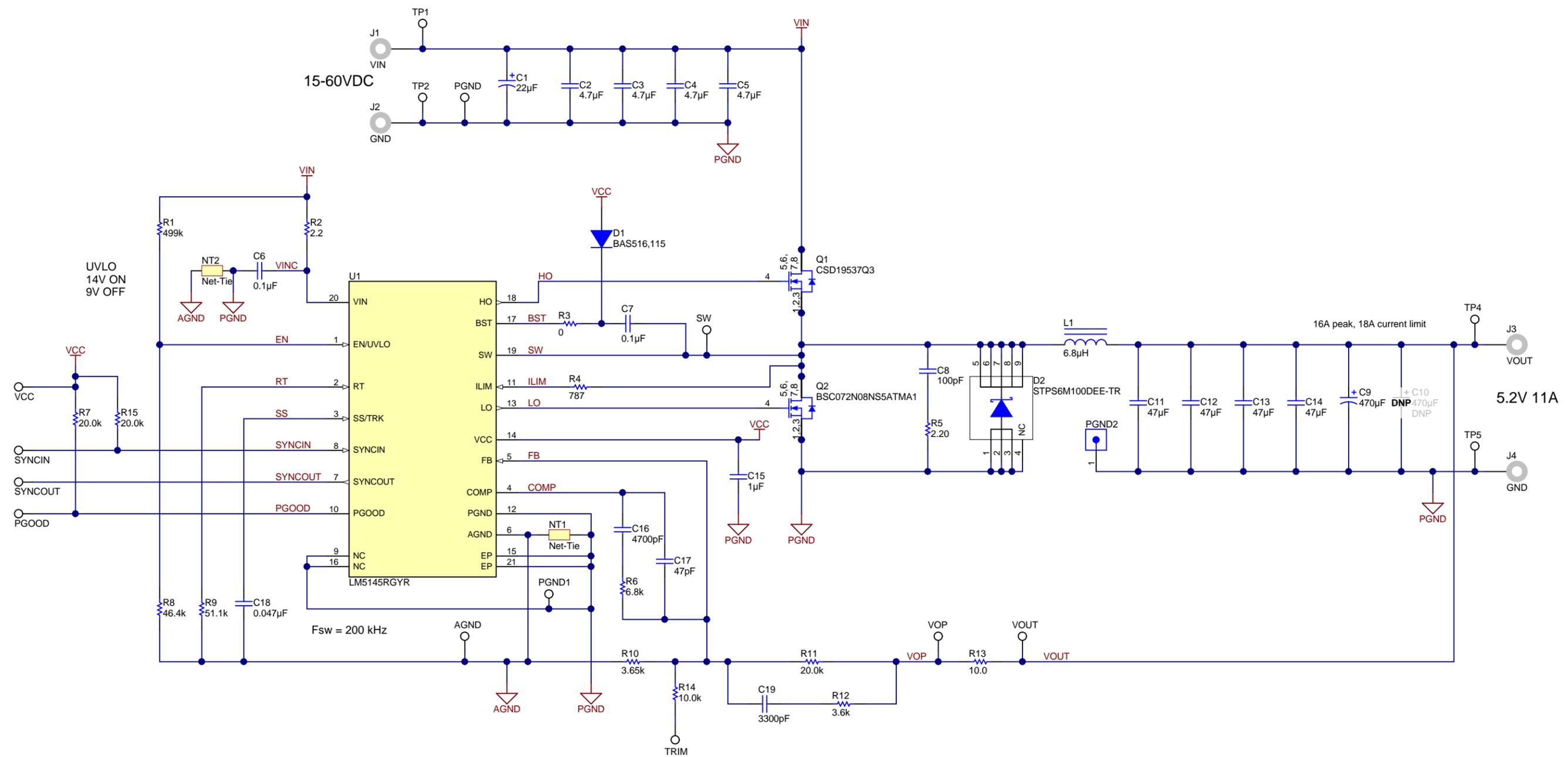


Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: N/A	Designed for: Public Release	Mod. Date: 12/1/2017
TID #: PMP20178	Project Title: LM5145 Synchronous Buck	
Number: PMP20178	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: PMP20178_REVA_Sh1.SchDoc	Size: B
Engineer: R. Sheehan	Contact: http://www.ti.com/support	



H1 NY PMS 440 0025 PH
H2 NY PMS 440 0025 PH
H3 NY PMS 440 0025 PH
H4 NY PMS 440 0025 PH

H5 1902C
H6 1902C
H7 1902C
H8 1902C

DNP FID1
DNP FID2
DNP FID3

PCB Number: PMP20178
PCB Rev: A



CAUTION HOT SURFACE

PCB LOGO
FCC disclaimer

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 5/14/2016
TID #: PMP20178	Project Title: LM5145 Synchronous Buck	
Number: PMP20178	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2
Drawn By:	File: PMP20178_REVA_Sh2.SchDoc	Size: B
Engineer: R. Sheehan	Contact: http://www.ti.com/support	

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